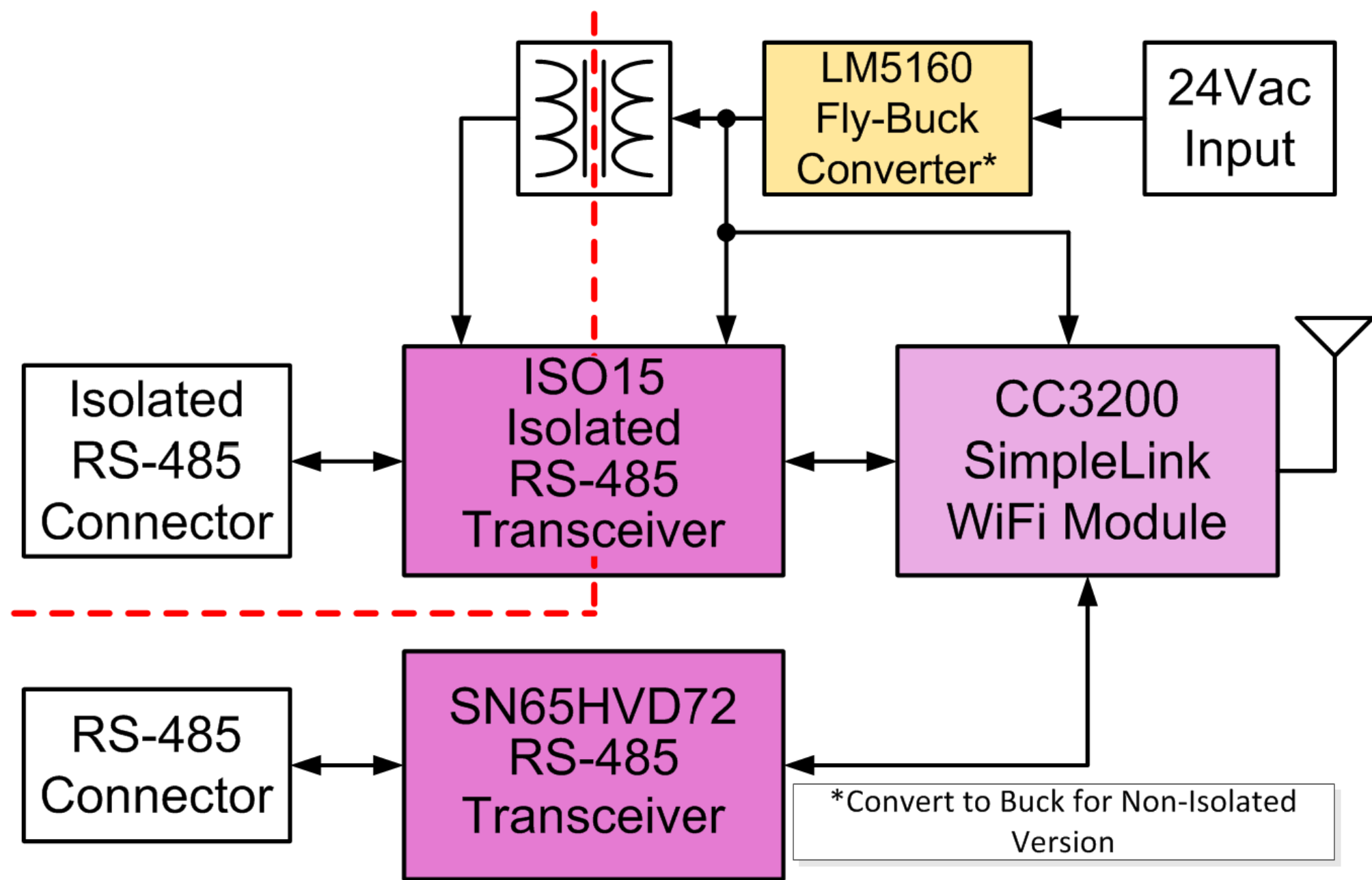


Revision History	
Revision	Notes
E3	E3: Added Drill Table to FAB drawing E2: Updated Footprint for L1, C9 changed to 4.7nF



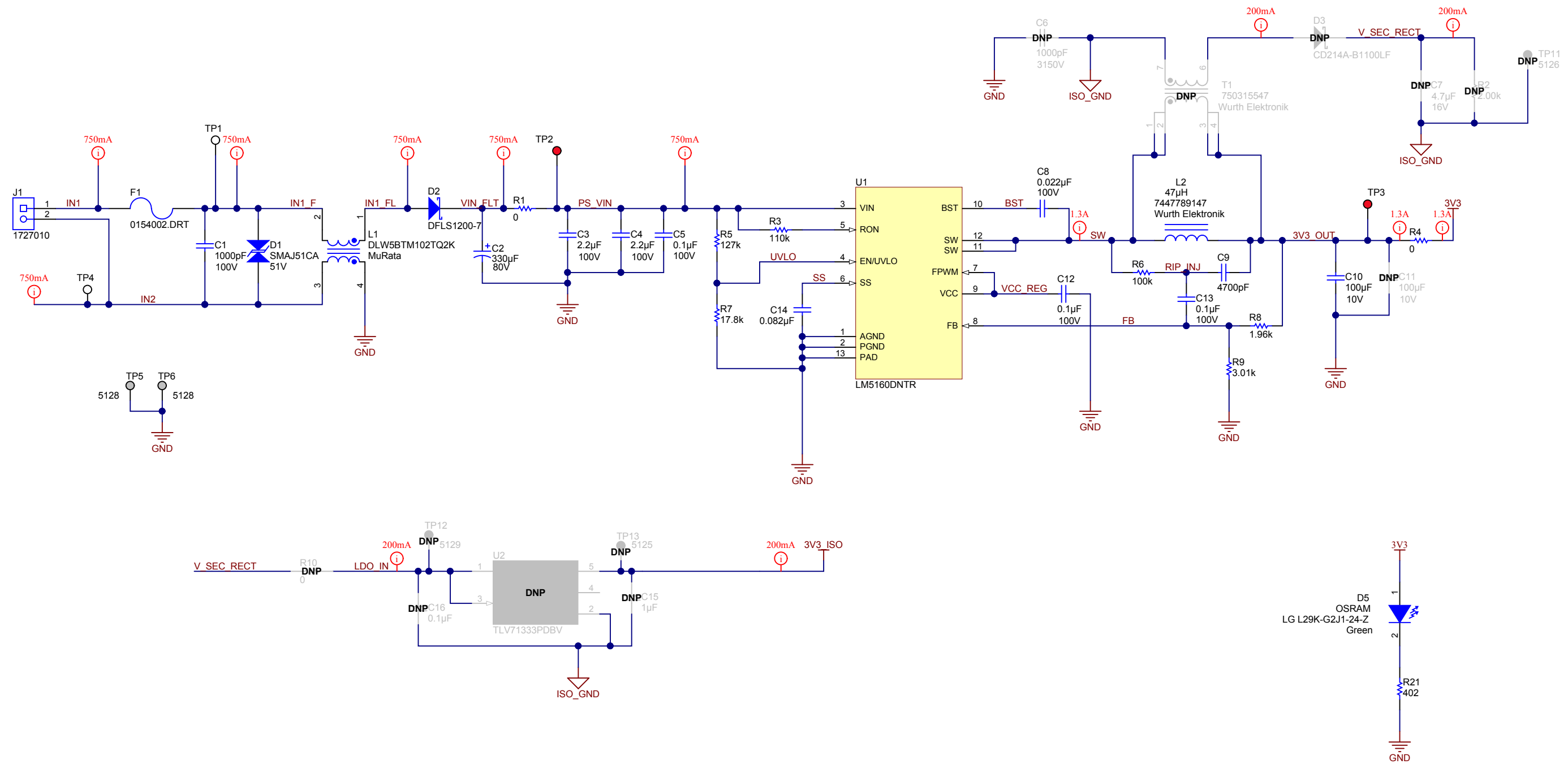
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TID #: TIDA-00485	Project Title: RS-485 To Wi-Fi Bridge with 24 VAC Power	Sheet: 1 of 5	
Number: ISE4037	Rev: E3	Assembly Variant: 002	http://www.ti.com
SVN Rev: Version control disabled	File: ISE4037_RS485_to_WiFi_Sheet1.SchDoc	Size: B	© Texas Instruments 2015
Drawn By:	Engineer: M. Knapp	Contact: http://www.ti.com/support	

Variant Key:

Variant 001 has an isolated RS-485 interface and a Fly-Buck power supply with an isolated secondary.

Variant 002 has a non-isolated RS-485 interface and a simple Buck power supply.



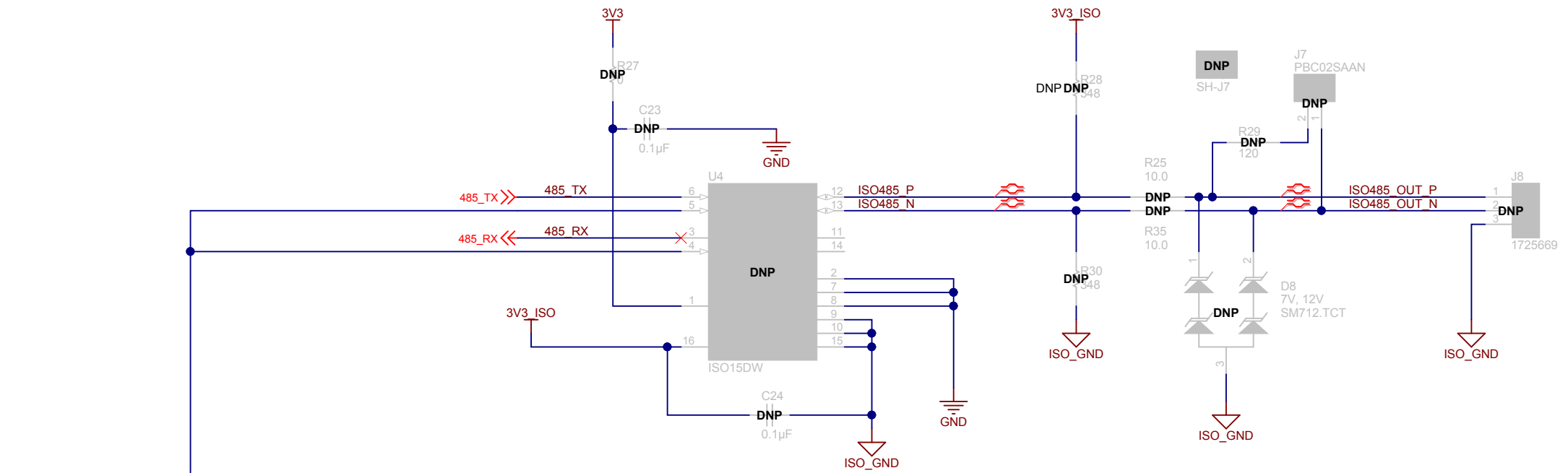
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Drawn By:	File: ISE4037_RS485_to_WiFi_Sheet2.SchDoc	Size: B
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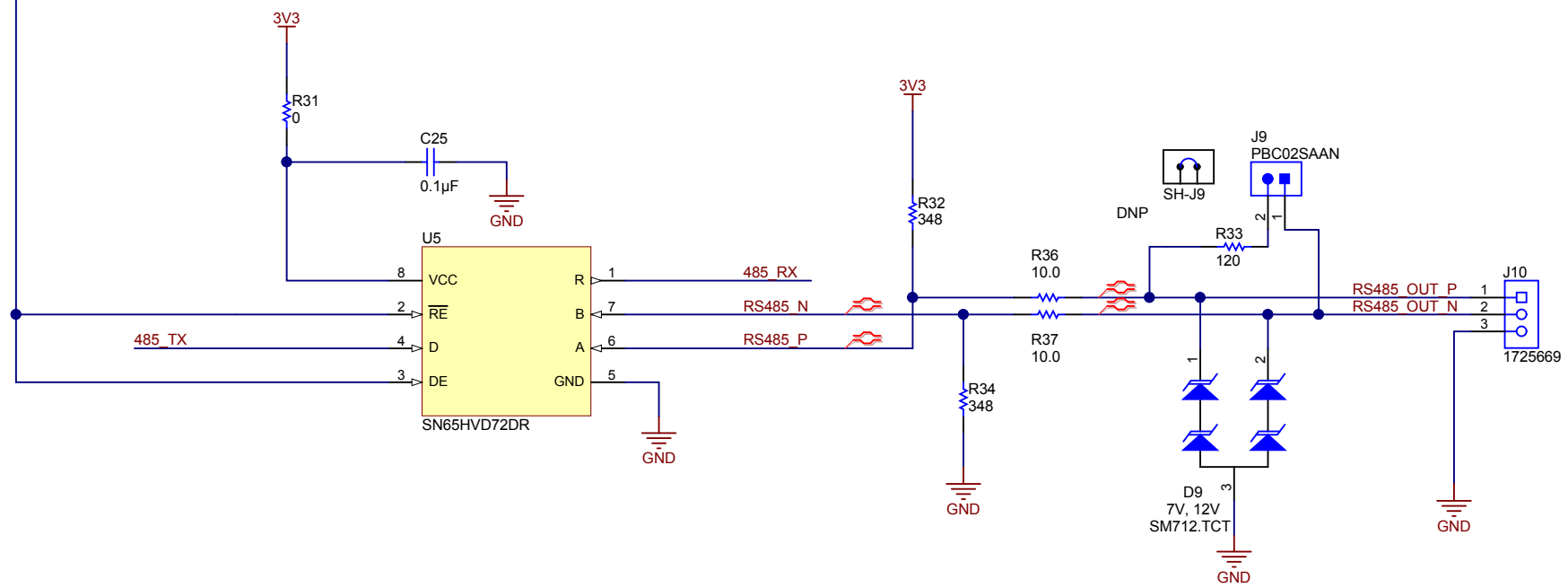


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Number: ISE4037	Rev: E3	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 002	Sheet: 4 of 5
Drawn By:	File: ISE4037_RS485_to_WiFi_Sheet4.SchDoc	Size: B
Engineer: M. Knapp	Contact: http://www.ti.com/support	© Texas Instruments 2015



H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3

PCB Number: ISE4037
PCB Rev: E3

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

PCB LOGO
CAUTION. READ USER GUIDE BEFORE USE

Label Table	
Variant	Label Text
001	Serial Number
002	Serial Number


ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4
Assembly Note
Place SH-J6 on J6, SH-J7 on J7, and SH-J9 on J9

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Number: ISE4037	Rev: E3	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 002	Sheet: 5 of 5	
Drawn By: M. Knapp	File: ISE4037_RS485_to_WiFi_Sheet5.SchDoc	Size: B	
Engineer: M. Knapp	Contact: http://www.ti.com/support		

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